



Practical Guide to the Packaging of Electronics: Thermal and Mechanical Design and Analysis (Hardback)

By Ali Jamnia

Taylor Francis Inc, United States, 2009. Hardback. Book Condition: New. 2nd Revised edition. 236 x 157 mm. Language: English . Brand New Book. As the demand for packaging more electronic capabilities into smaller packages rises, product developers must be more cognizant of how the system configuration will impact its performance. Practical Guide to the Packaging of Electronics: Second Edition, Thermal and Mechanical Design and Analysis provides a basic understanding of the issues that concern the field of electronics packaging. First published in 2003, this book has been extensively updated, includes more detail where needed, and provides additional segments for clarification. This volume supplies a solid foundation for heat transfer, vibration, and life expectancy calculations. Topics discussed include various modes of heat removal, such as conduction, radiation, and convection; the impact of thermal stresses; vibration and the resultant stresses; shock management; mechanical, electrical, and chemically induced reliability; and more. Unlike many other available works, it neither assumes the reader's familiarity with the subject nor is it so basic that the reader may lose interest. Dr. Ali Jamnia has published a large number of engineering papers and presentations and is the holder of a number of patents and patent applications. He...



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Reviews

This publication may be really worth a go through, and a lot better than other. It really is written in simple terms and never difficult to understand. Once you begin to read the book, it is extremely difficult to leave it before concluding.

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This book will not be simple to get going on reading but extremely exciting to read through. Yes, it can be play, still an interesting and amazing literature. I am very easily could possibly get a delight of reading a written book.

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